

Title of Change:	Packaging change for TO263 products.					
Effective date:	24 May 2018					
Contact information:	Contact your local ON Semiconductor Sales Office or < <u>Christian.remoreras@onsemi.com</u> >					
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.					
Change category:	Wafer Fab Change Assembly Change Test Change Other: <u>Packaging</u>					
Change Sub-Category(s): Manufacturing Site Change/Ad Manufacturing Process Change						
Sites Affected:	ON Semiconductor Sites : ON Cebu, Philippines			External Foundry/Subcon Sites: None		
Description and Purpose:						
ON Semiconductor, Cebu, Philippines announces the change in packaging for TO263 package in term of the number of empty for the leader and trailer tapes inside the reel. This is to ensure that additional protection of the units near the reel hub from damage during mishandling of boxes (dropp ed) which result to lifted leads by increasing the number of empty pockets of the trailer tape.						
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		Trailer Empty pockets Leade		Leade	r Empty Pockets	
	Current	55			70	
	Proposed Change	90			25	
List of Affected Parts:						
	FDB070AN06A0-F085		F	FGB3040G2-F085		
	FDB075N15A-F085		HUF76419S3			
	FDB14AN06LA0-F085			HUFA75639S3ST		
	FDB2532-F085		HUFA76645S3ST-FC		S3ST-F085	
	FDB7030BL		ISL9V2540S3ST		40S3ST	
	FDB8030L		I	ISL9V5036S3ST		
	FDB8442-F085			NDB6020P		
	FDB86360-F085			NDB60	30PL	
	FDB8880			NDB6060L		
	FDB9406-F085					
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